LNJ218C8ARA

Surface Mounting Chip LED

Dome-Lens Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Symbol Rating		
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

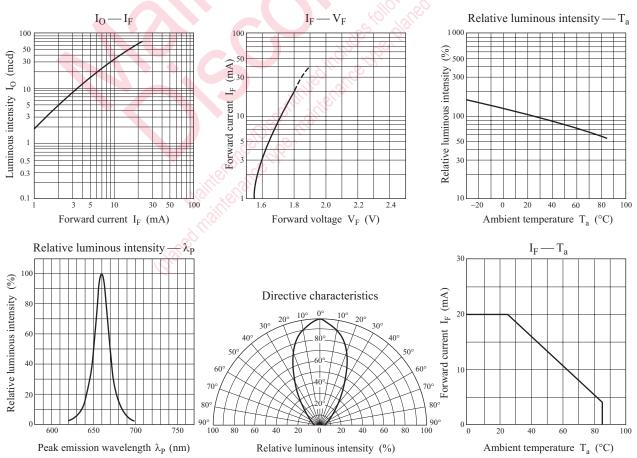
Lighting Color

• Red

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) *: The condition of I_{FP} is duty 10%, Pulse	e width 1 mse	ec.						
Electro-Optical Characteristics T _a	= 25°C±3°	С					~°\	5,77
Parameter	Symbol		Conditions	N	∕lin	Тур	Max	Unit
Luminous intensity *	Io	$I_F = 10 \text{ mA}$			17	32	S. C.	mcd
Reverse current	I _R	$V_R = 3 V$				~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		Ő	30.7	1.72	2.50	V
Peak emission wavelength	λ_P	$I_F = 10 \text{ mA}$			all of the	660		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		10 ¹ 01	<u>0</u> ,	20		nm

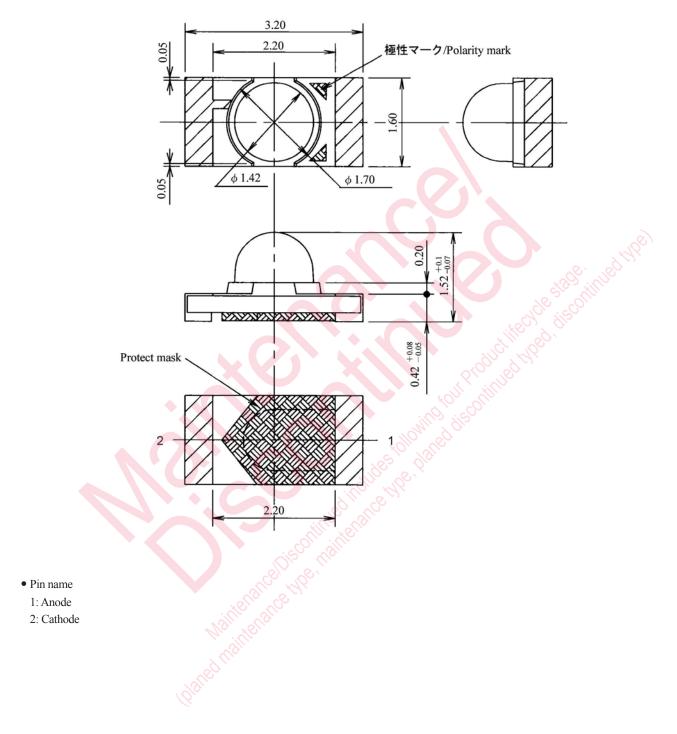
Note) *: Measurement tolerance: $\pm 20\%$



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Package (Unit: mm)

KLTLTN2K1800



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